LNJC36X8ARA1

Hight Bright Surface Mounting Chip LED

ESS Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

| Parameter | Symbol | Rating | Unit | |
|-------------------------------|------------------|-------------|------|--|
| Power dissipation | P _D | 40 | mW | |
| Forward current | I _F | 10 | mA | |
| Pulse forward current * | I _{FP} | 40 | mA | |
| Reverse voltage | V _R | 5 | V | |
| Operating ambient temperature | T _{opr} | -30 to +85 | °C | |
| Storage temperature | T _{stg} | -40 to +100 | °C | |

Lighting Color

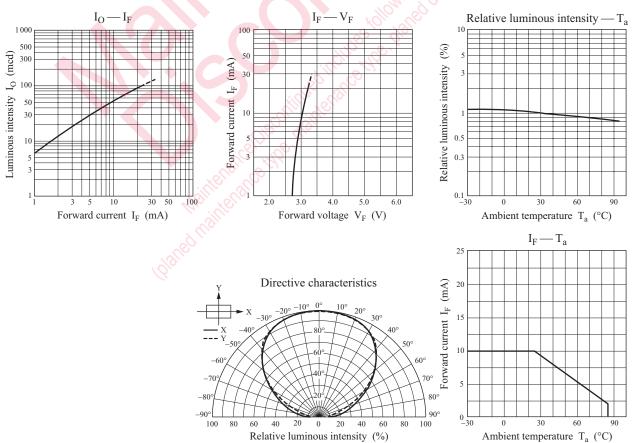
• Ice Blue

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|--------------------------|----------------|-----------------------------|-------|-------|-------|------|
| Luminous intensity * | I _O | $I_{\rm F} = 5 \mathrm{mA}$ | 25 | 30 | 56 | mcd |
| Reverse current | I _R | $V_R = 5 V$ | | 5, 72 | 10 | μΑ |
| Forward voltage | V _F | $I_F = 5 \text{ mA}$ | ~JCL | 2.9 | 3.2 | V |
| Chromaticity coordinates | x | $I_{\rm F} = 5 {\rm mA}$ | 0.171 |) | 0.240 | |
| | у | $I_{\rm F} = 5 {\rm mA}$ | 0.104 | | 0.202 | |

Note) *: Measurement tolerance: ±20%

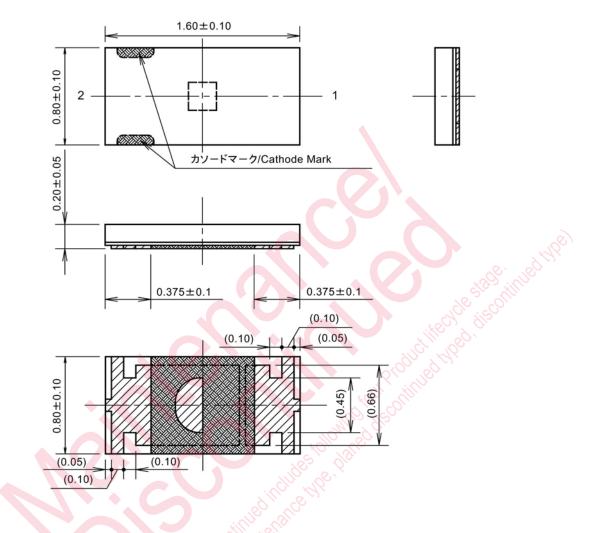


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Panasonic

Package (Unit: mm)

KLTFTN2K3600



- Pin name
 - 1: Anode
 - 2: Cathode

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